

# **METHOD FOR RECONSTRUCTING AN INTEGRATED CIRCUIT PACKAGE USING LAPPING**

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## **ABSTRACT**

A method is provided for reconstructing an integrated circuit package  
5 comprising: attaching a die to exposed wire bond pads of a lead frame so that the  
die is electrically connected to the lead frame; and encapsulating the die and the  
wire bond pads in an encapsulant; and reshaping an upper surface of the  
encapsulant where at least a portion of the encapsulant reshaping is performed by a  
lapping process.

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